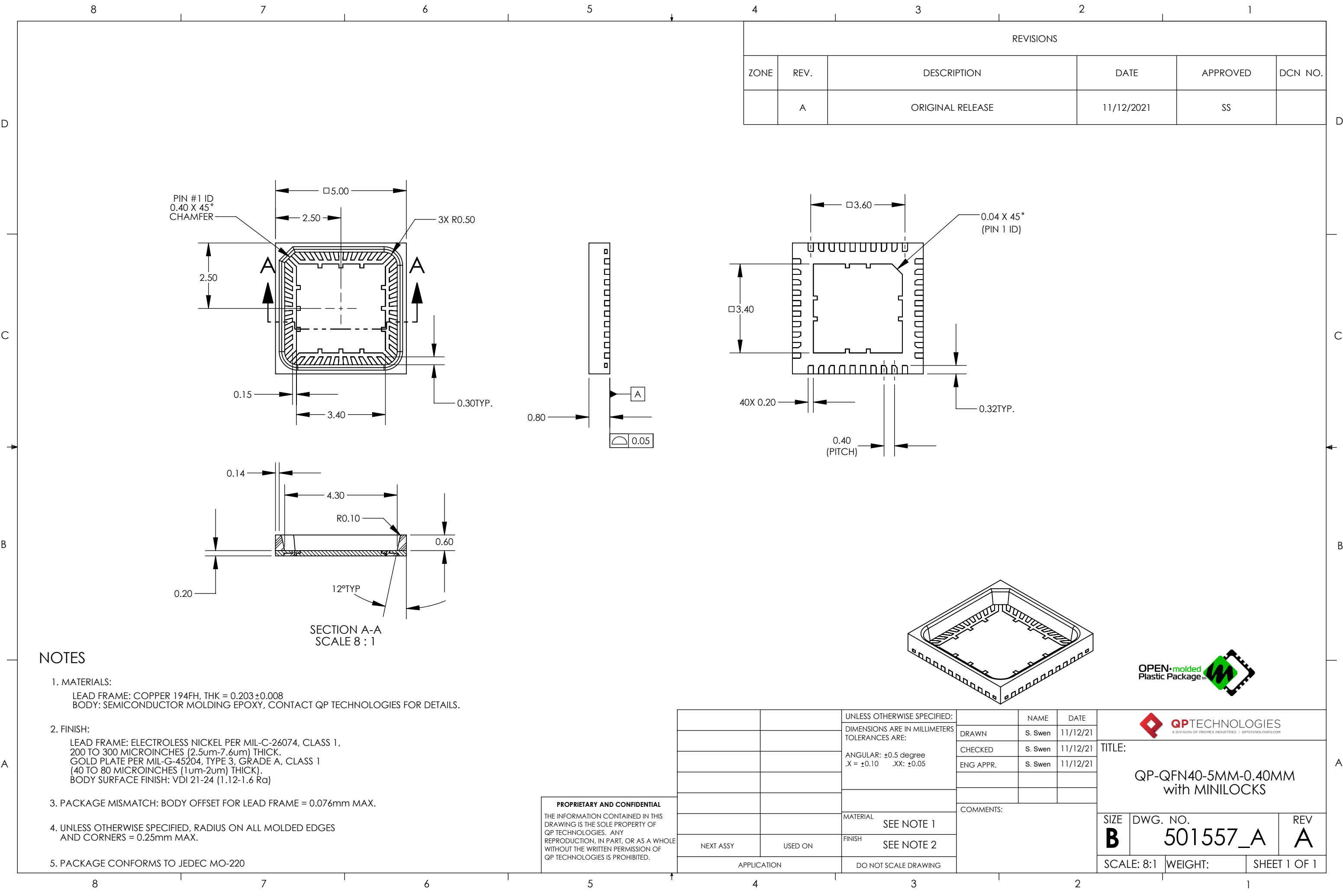
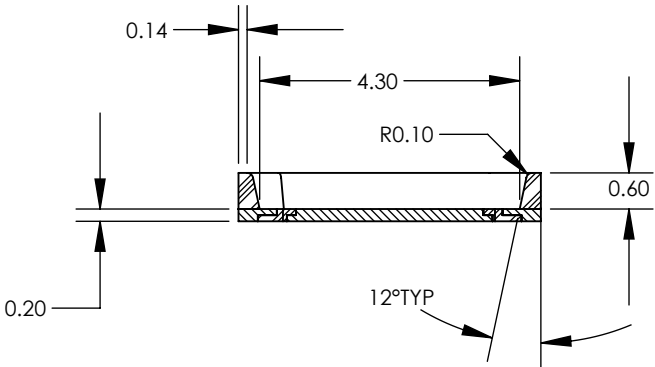
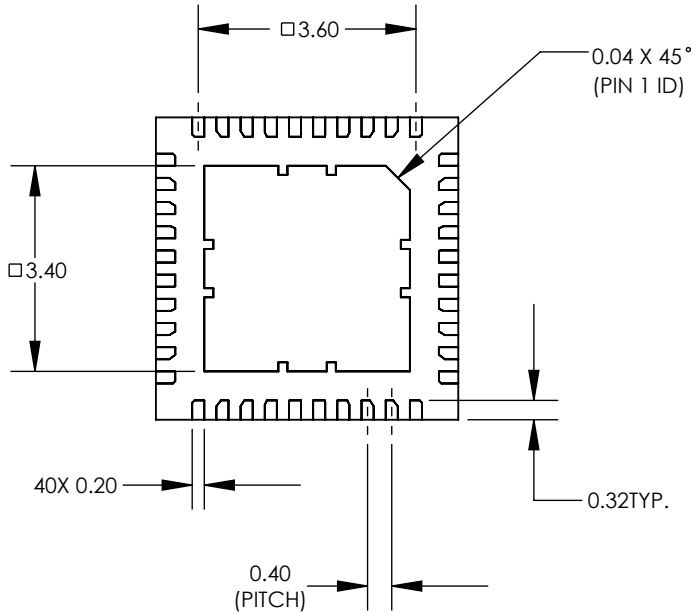
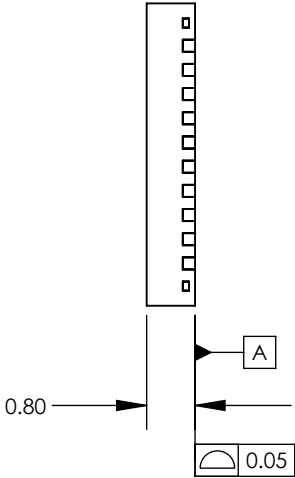
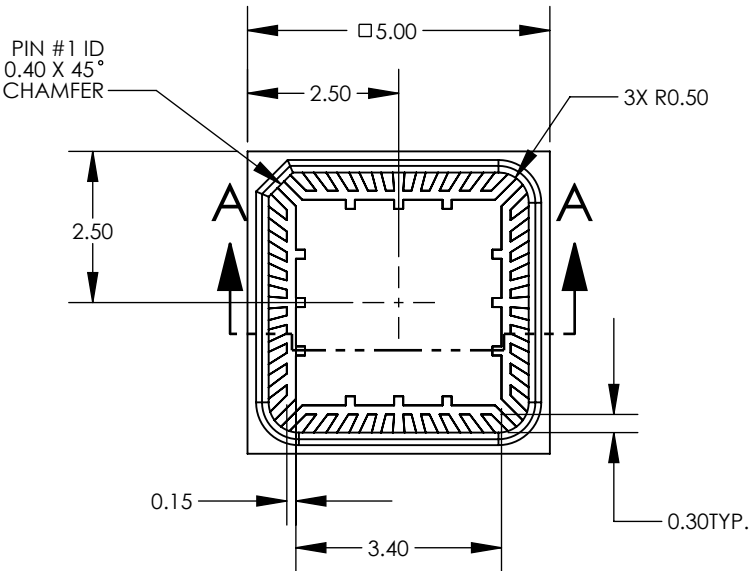
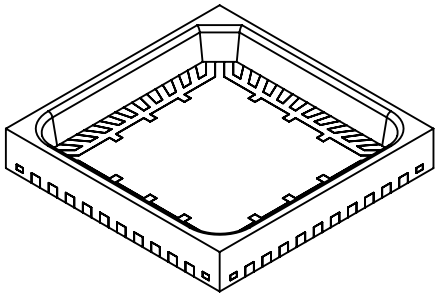




REVISIONS					
ZONE	REV.	DESCRIPTION	DATE	APPROVED	DCN NO.
	A	ORIGINAL RELEASE	11/12/2021	SS	



SECTION A-A
SCALE 8 : 1



NOTES

- MATERIALS:
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QP TECHNOLOGIES FOR DETAILS.
- FINISH:
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICROINCHES (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.
- PACKAGE CONFORMS TO JEDEC MO-220

PROPRIETARY AND CONFIDENTIAL
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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: ANGULAR: ±0.5 degree .X = ±0.10 .XX: ±0.05		NAME	DATE	 QPTECHNOLOGIES A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM		
			DRAWN	S. Swen	11/12/21	TITLE: QP-QFN40-5MM-0.40MM with MINILOCKS		
			CHECKED	S. Swen	11/12/21			
			ENG APPR.	S. Swen	11/12/21			
						SIZE B		
		MATERIAL	SEE NOTE 1			DWG. NO.		REV
		FINISH	SEE NOTE 2			501557_A		A
NEXT ASSY	USED ON							
APPLICATION		DO NOT SCALE DRAWING				SCALE: 8:1	WEIGHT:	SHEET 1 OF 1